# **BGA Heat Sink - High Performance Device Specific - NXP**





\*Image above is for illustration purpose only.

ATS Part#: ATS-59002-C1-R0

Description: 25.00 x 32.00 x 13.00 mm BGA Heat Sink - High Performance Device Specific - NXP

Heat Sink Type: NXP

Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-59002-C2-R0 Discontinued

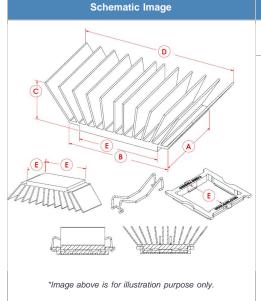
## **Features & Benefits**

- Designed for flip-chip processors such as NXP MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- · Comes preassembled with high performance, phase changing, thermal interface material

### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	6.5 °C/W	5 °C/W	4.1 °C/W	3.6 °C/W	3.2 °C/W	3 °C/W	2.7 °C/W
	Ducted Flow	3.8	N/A	N/A	N/A	N/A	N/A	N/A

#### **Product Detail**



Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish	
25.00 mm	32.00 mm	13.00 mm	46.5 mm	T766	BLACK-ANODIZED	

#### Notes:

- Dimension A and B refer to component size.
- Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- ATS-59002-C2-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint Gobain C1100F). NOTE: Saint Gobain C1100F is discontinued effective 12/31/10.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT170
- Contact ATS to learn about custom options available.

